

# ***Ultra-Compact and Light Weight Intelligent Power Semiconductor Module for Hybrid System***

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- 1. Background of Development**
- 2. Design of Aluminum heat sink**
- 3. Development of high reliability solder material**
- 4. Conclusions**

## **1. Background of Development**

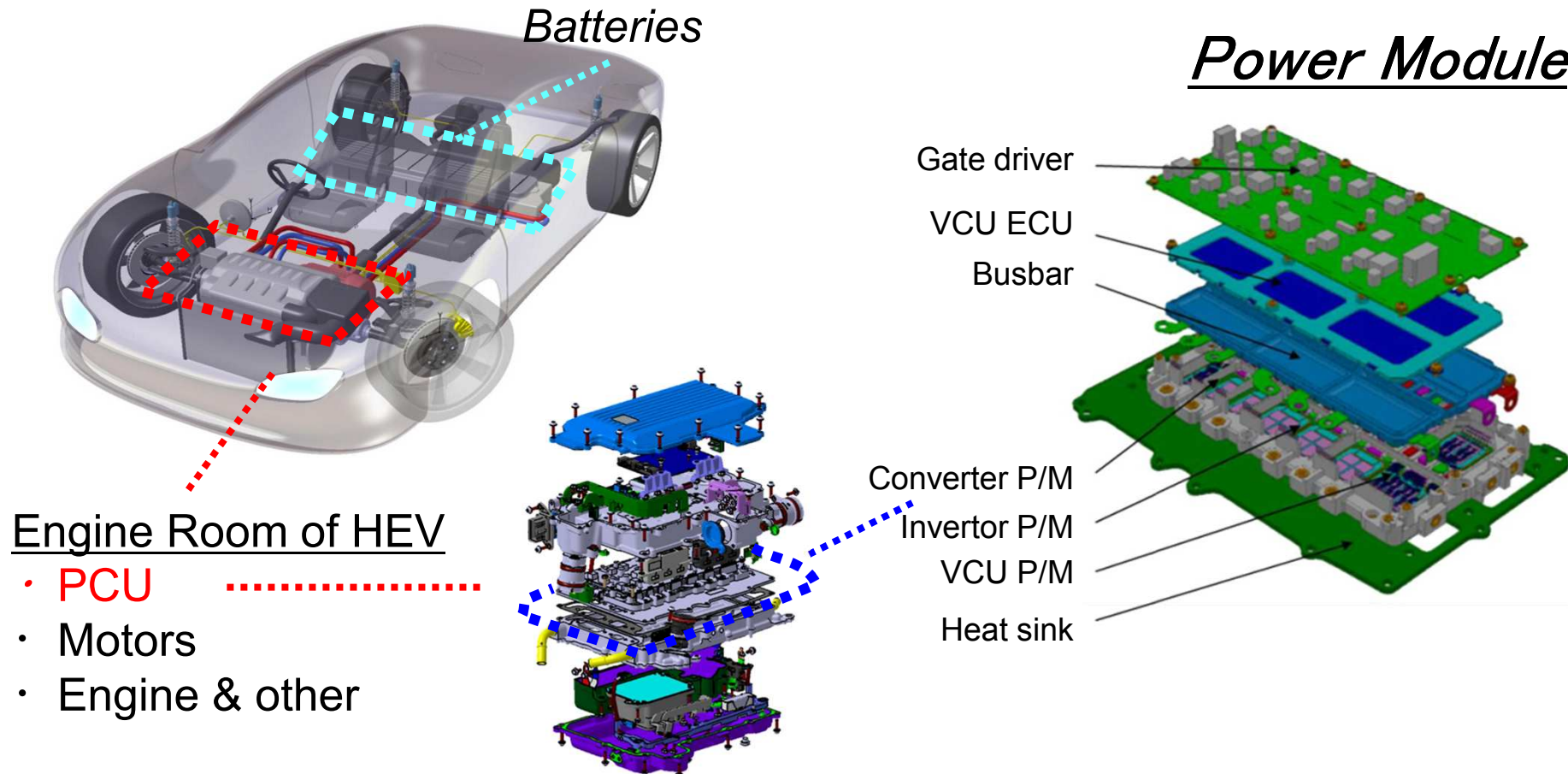
## 2. Design of Aluminum heat sink

## 3. Development of high reliability solder material

## 4. Conclusions

# Required Performance of Power Module for HEV

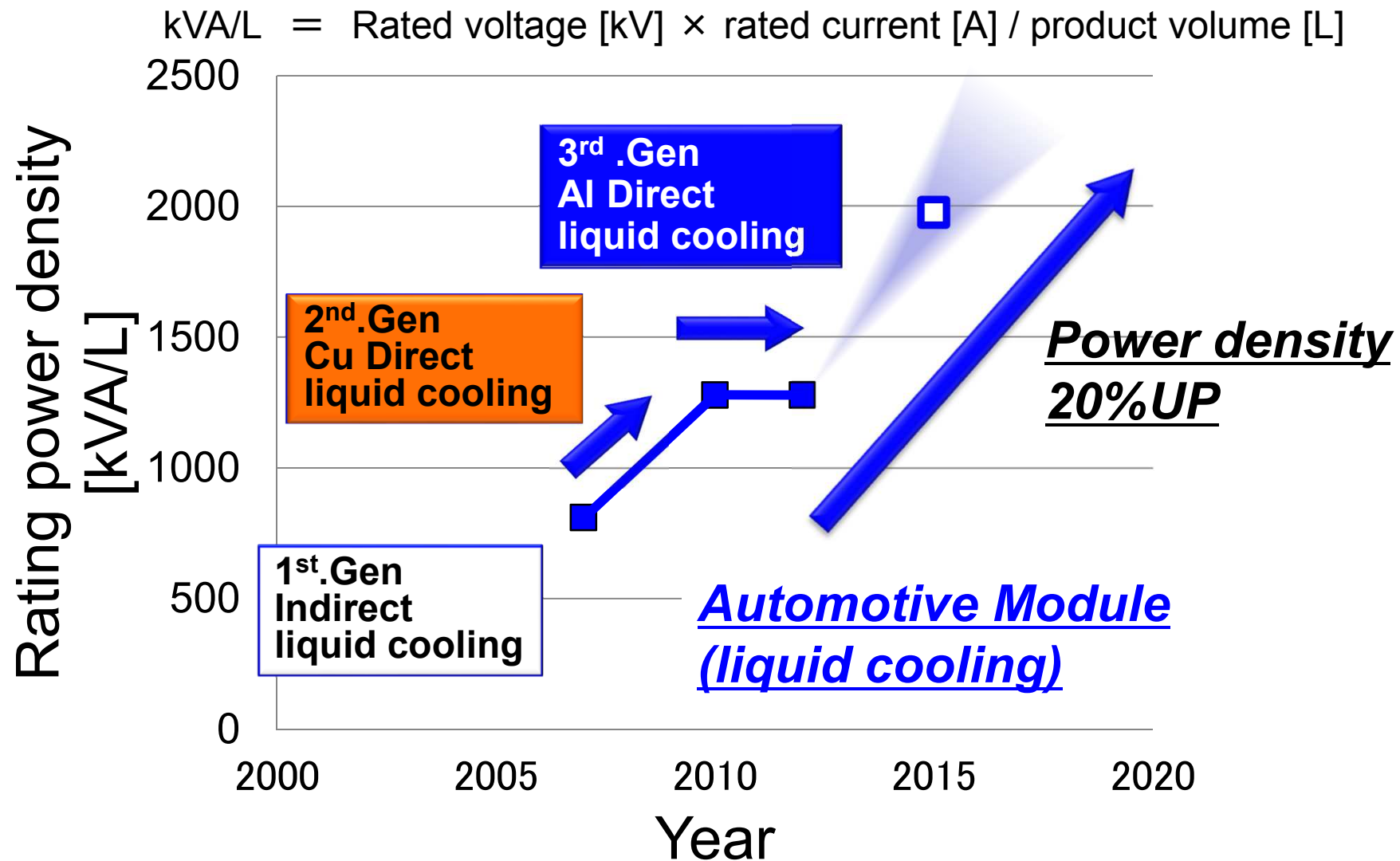
## Intelligent Power Module for Hybrid Electric Vehicles



### ■ Requirements for power module

1. High Efficiency, 2. Downsizing, 3. Lightweight

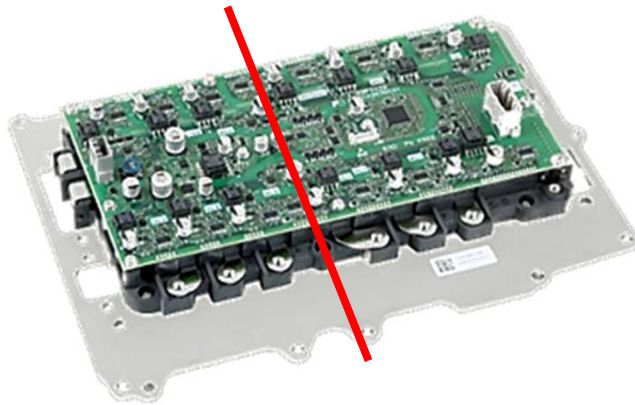
# Trend of Fuji Electric Power module



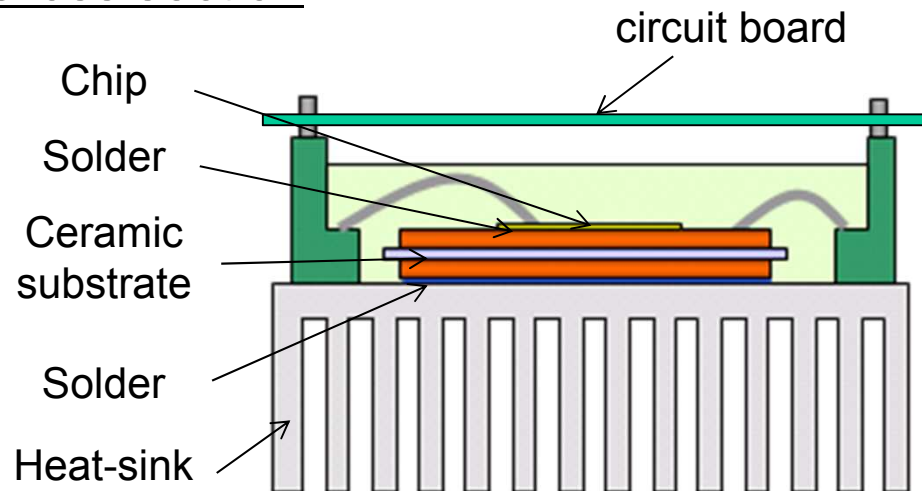
- High power density is required for automotive module
- Direct liquid cooling with aluminum fin is key technologies for 3<sup>rd</sup> gen.

# Subject of Conventional Power Module Structure

## Direct liquid cooling module structure

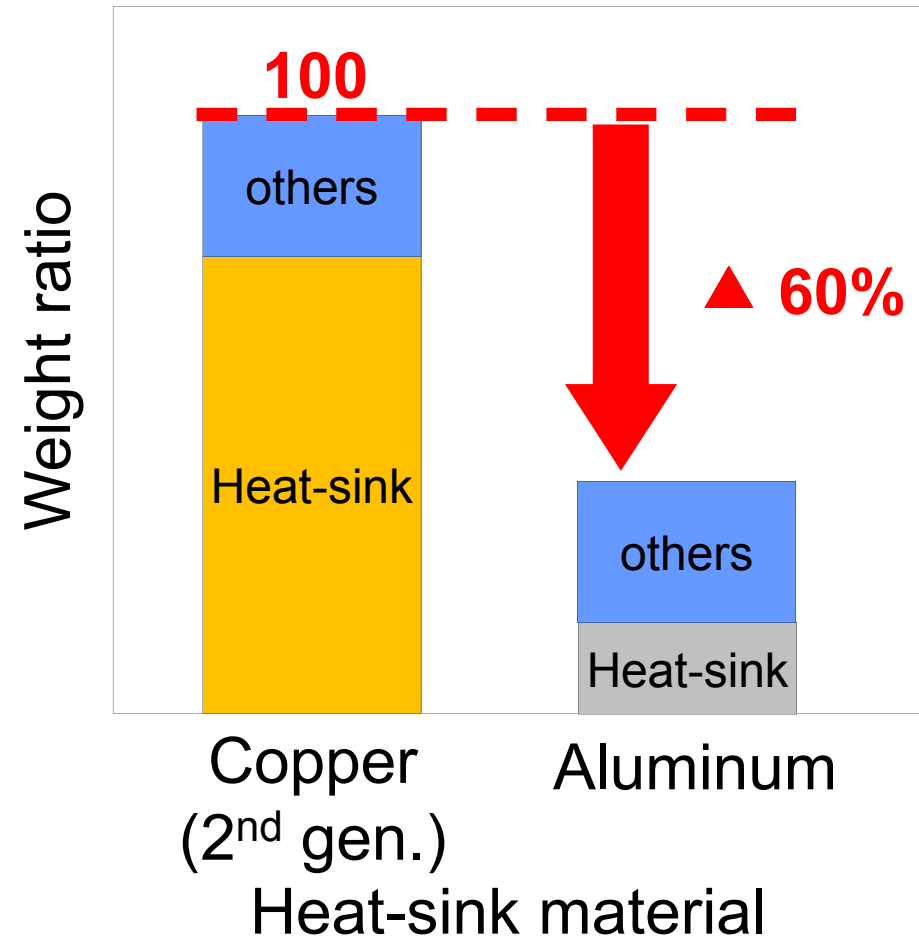


## Cross section



*Aluminum is*

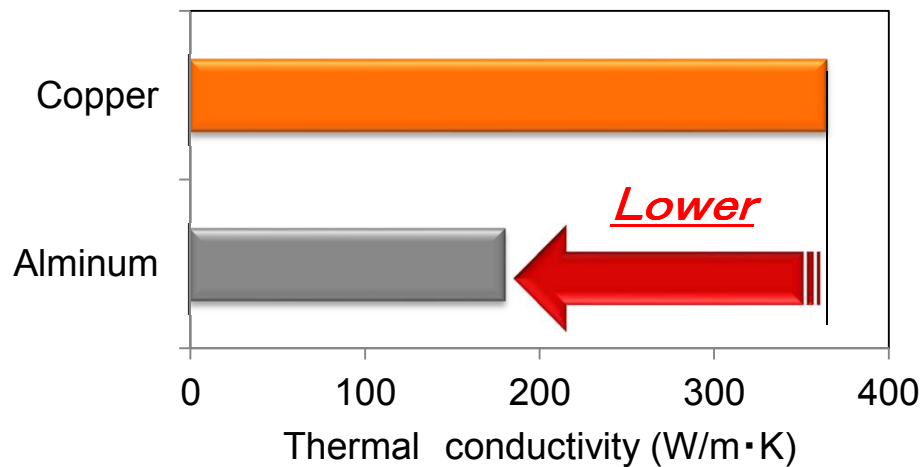
- *Light weight*
- *Good corrosion resistance*



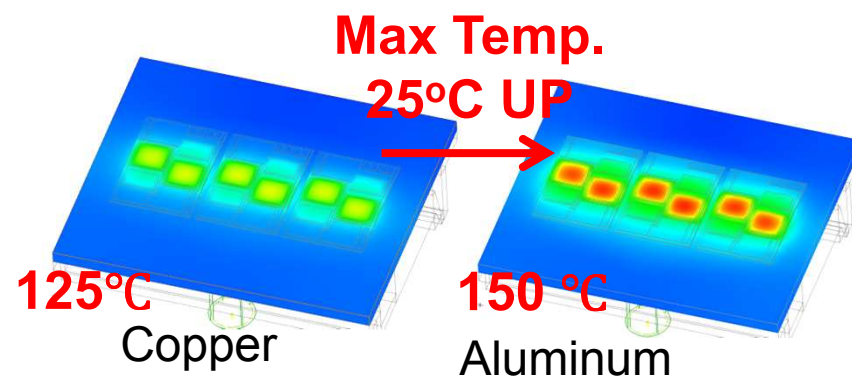
■ Aluminum heat sink can reduce module weight by 60%

# Subjects of Aluminum heat sink structure

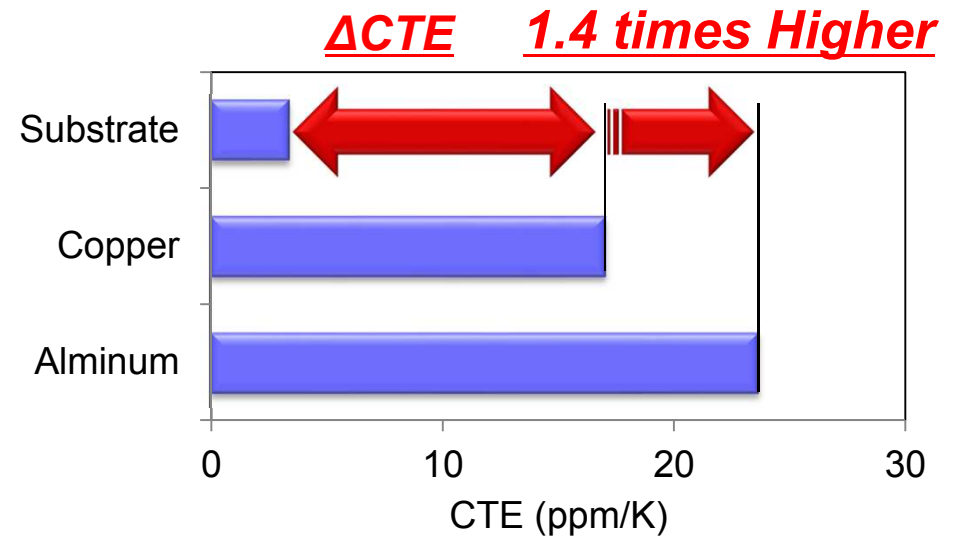
## I. Low thermal conductivity



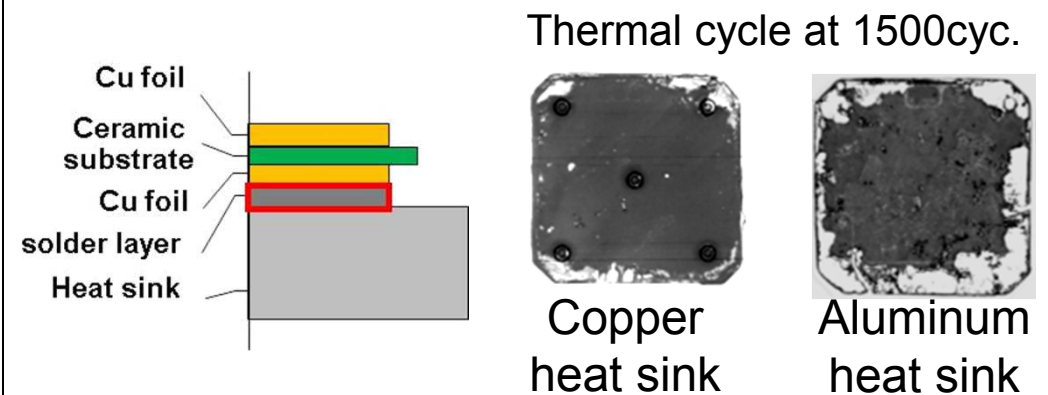
## Temperature of semiconductor



## II. Large CTE mismatch



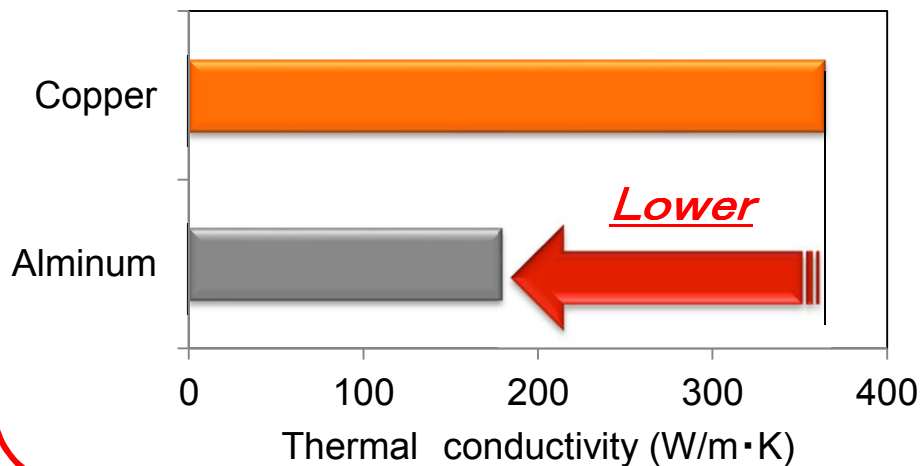
## Reliability of joint layer



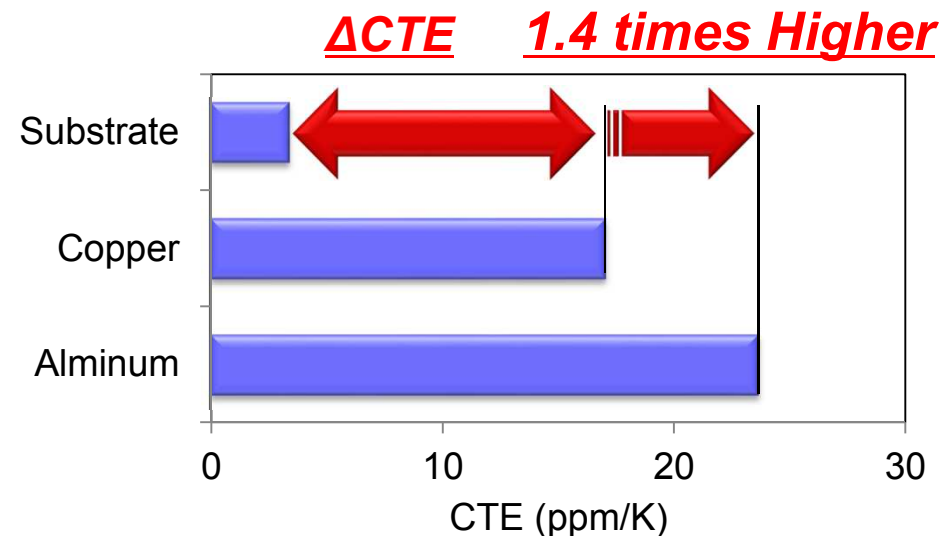
■ Thermal design and high strength joint layer are needed

1. Background of Development
- 2. Thermal design of Aluminum heat sink**
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## ***I. Low thermal conductivity***



## ***II. Large CTE mismatch***

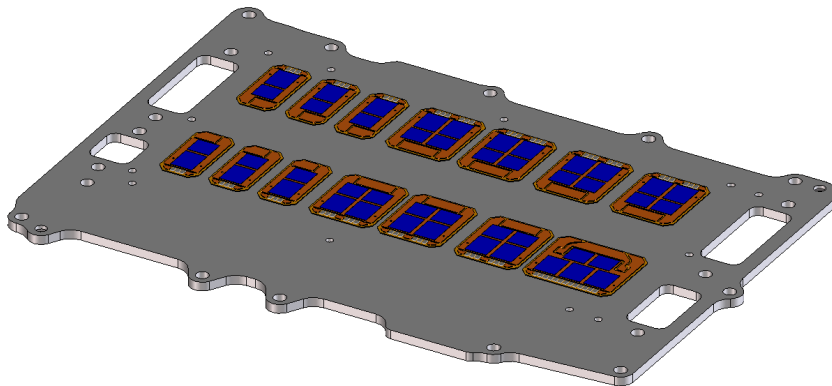




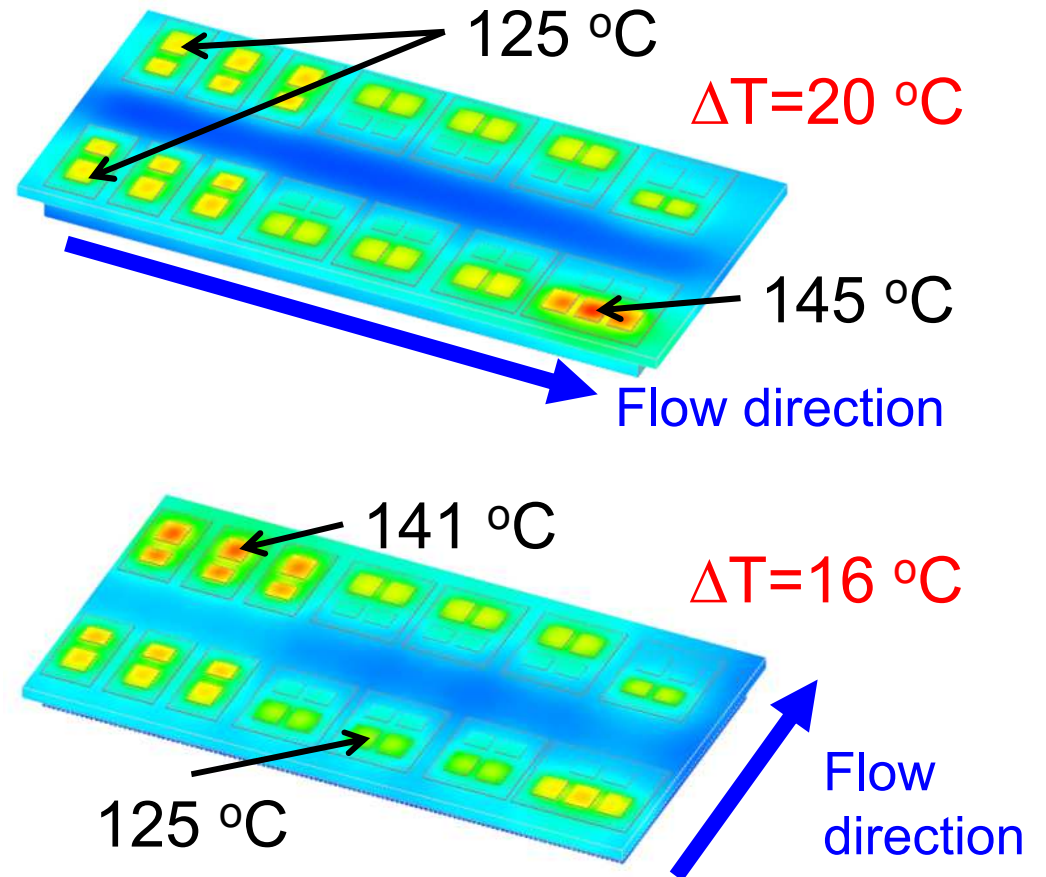
# Subject for the design of aluminum heatsink

## Simulation model (real product)

Size : 320x170 mm  
Inlet : 60 °C  
Flow speed : 10 l/min.  
Chip operation : maximum



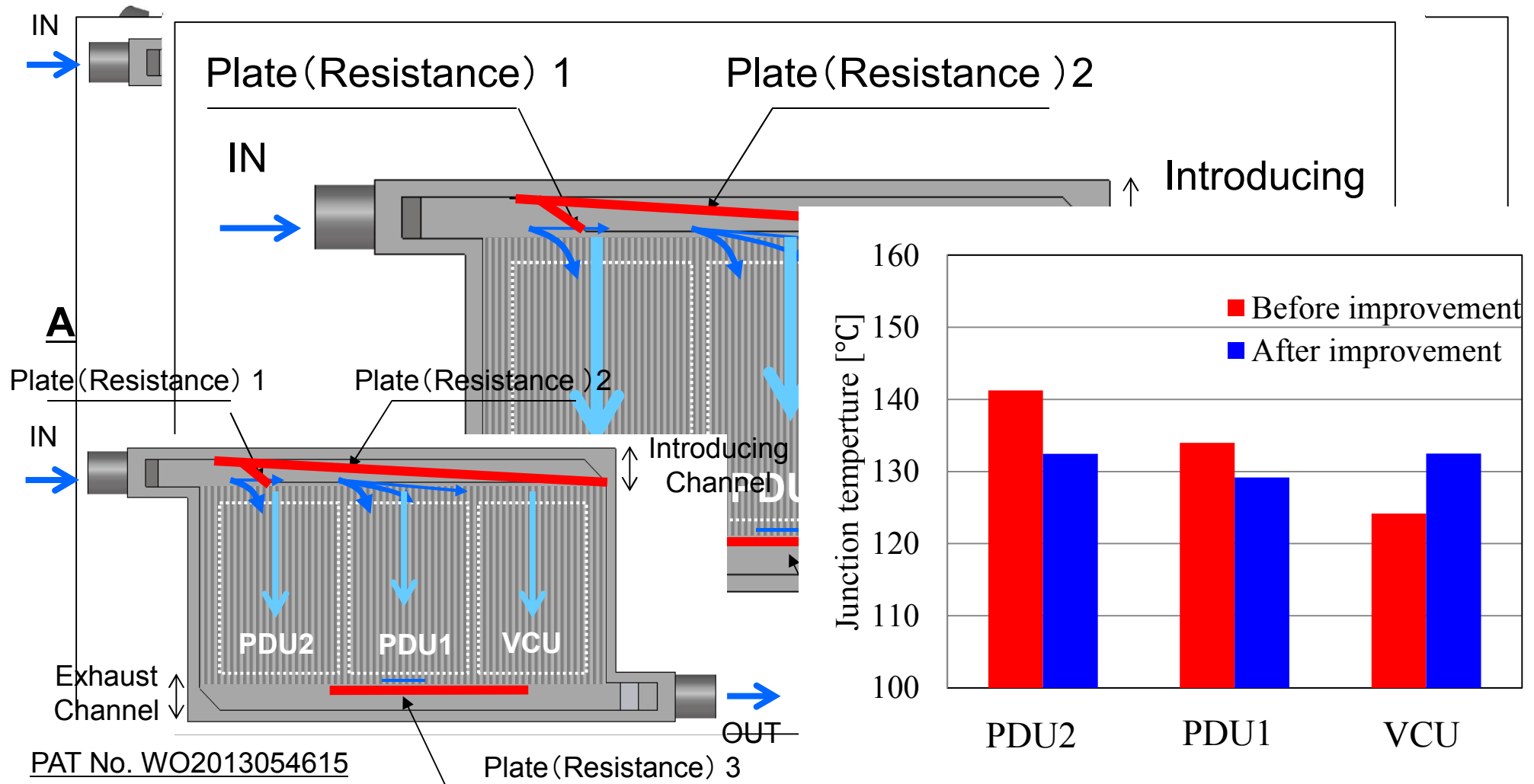
## Temperature distribution of coolant



■ Optimization is necessary to reduce temperature distribution

# Optimization of flow distribution

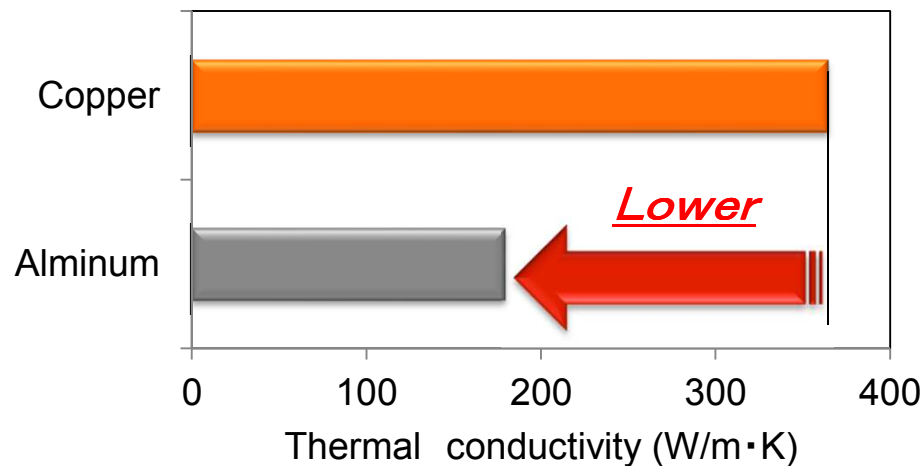
## Before Optimization



■ With this design, we have a almost the same performance with Aluminum heat sink as Copper heat sink.

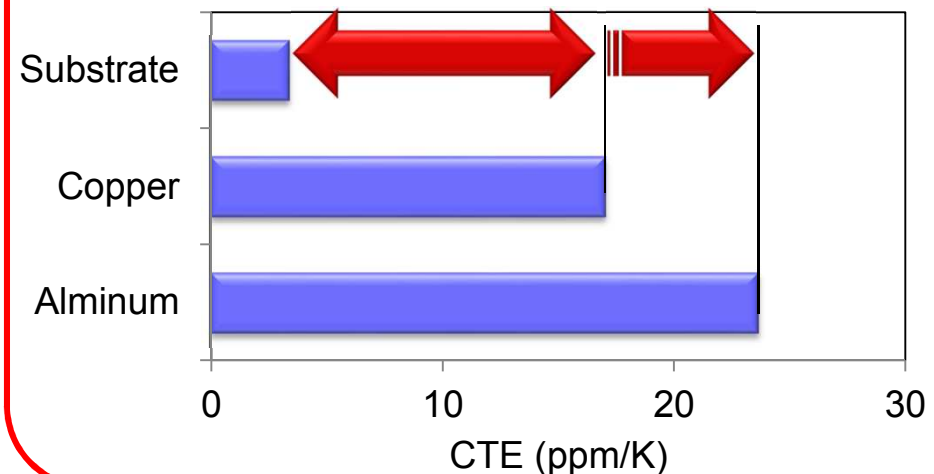
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## ***I. Low thermal conductivity***



## ***II. Large CTE mismatch***

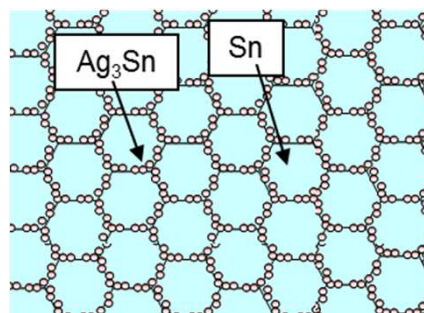
**$\Delta CTE$  1.4 times Higher**



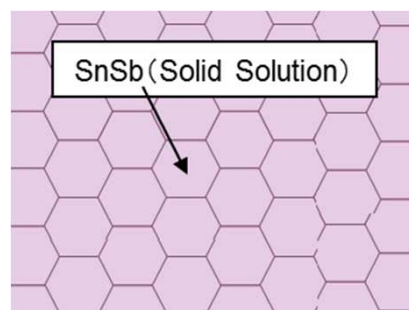
# Strengthening Mechanism of Solder Alloy

Aging condition  
175 °C  
1000 hours

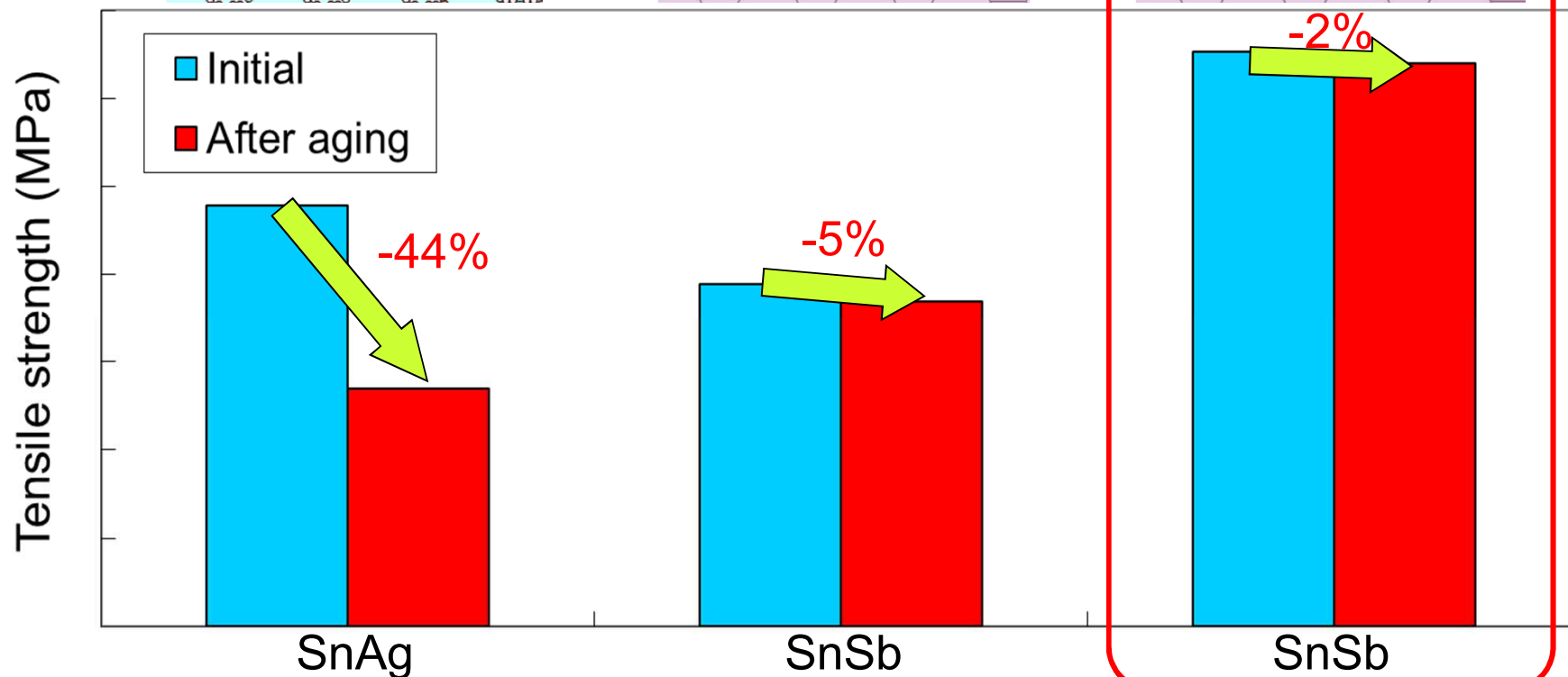
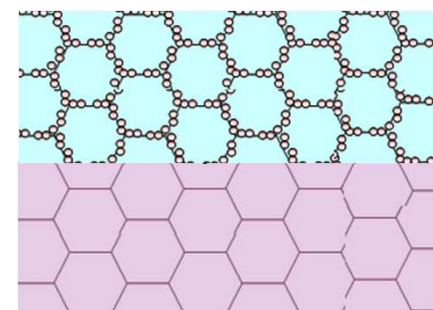
## Precipitation Strengthening



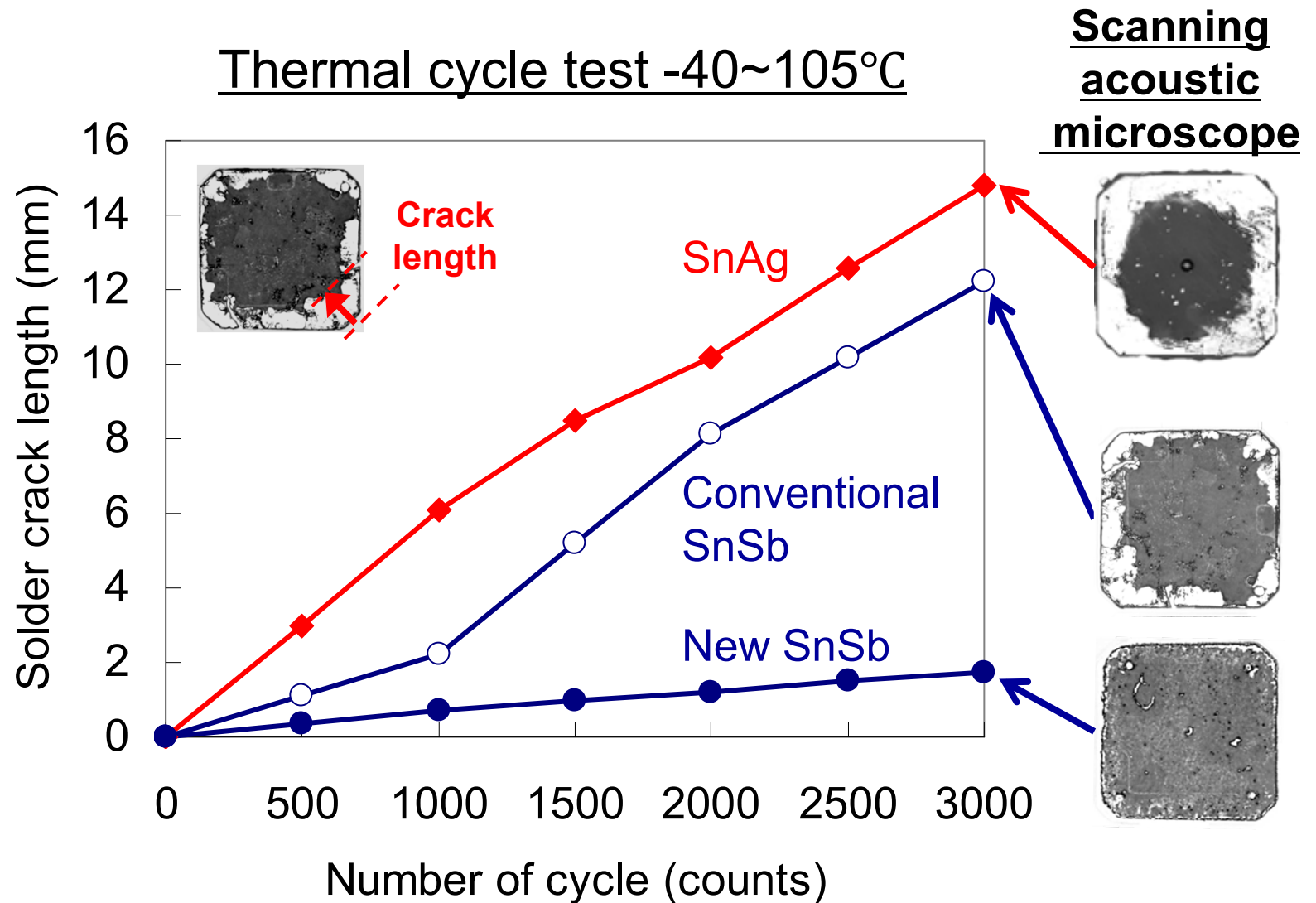
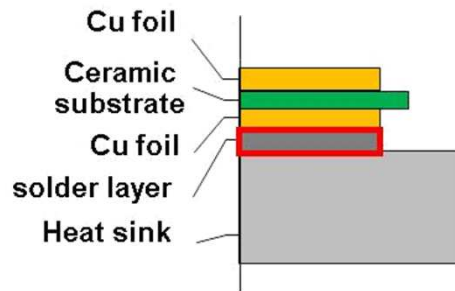
## Solid Solution Strengthening



## Combination Strengthening



# Effect of Thermal Fatigue Characteristics of New Solder



■ Achieved 7 times longer lifetime against the general Sn-Ag Solder.

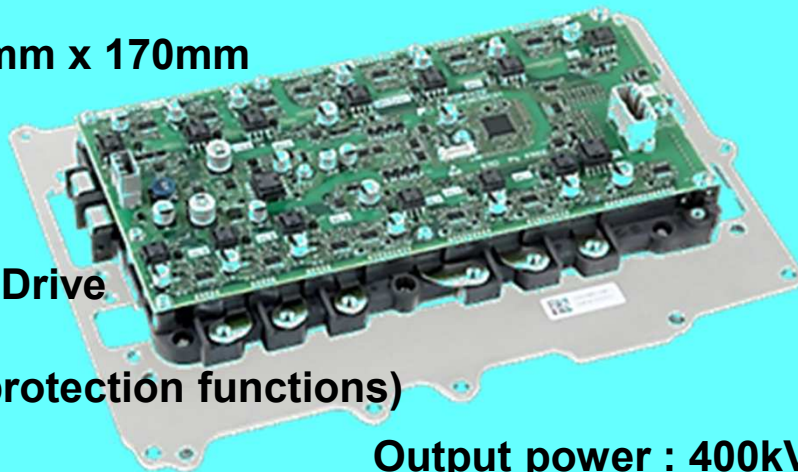


# Product Summary of a Newly Developed IPM

## Mass Production Model

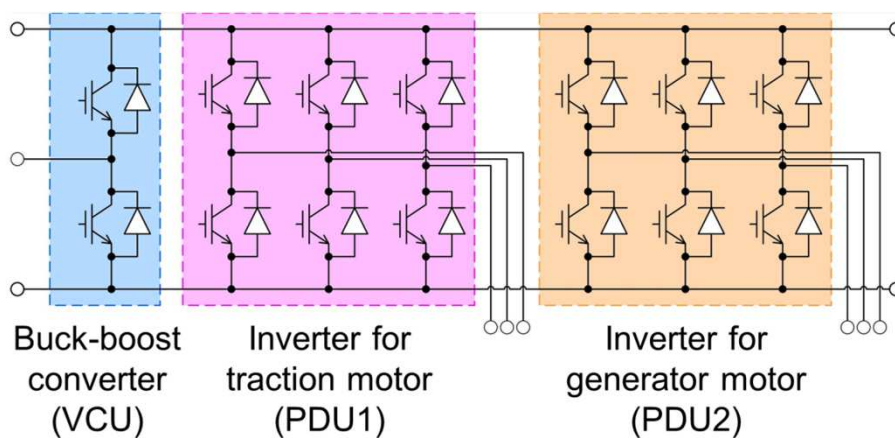
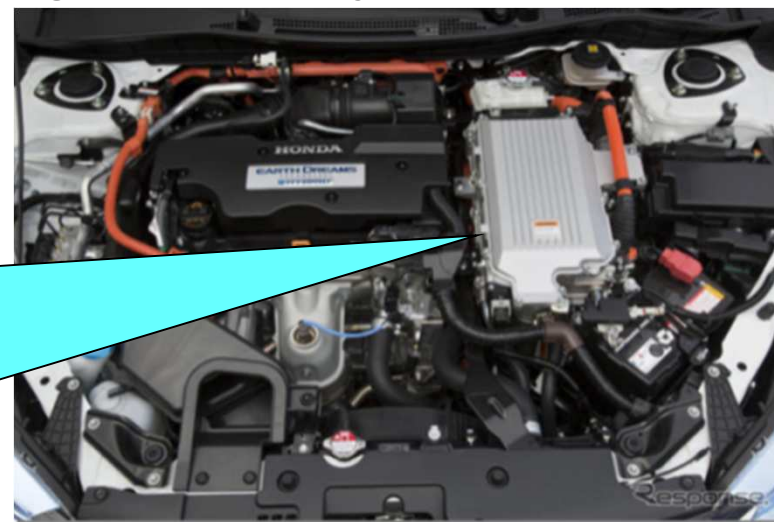
320mm x 170mm

Gate Drive  
ICs  
(for protection functions)



Output power : 400kVA

## Engine Room in hybrid Electric Vehicle



Unit	Specifications
<b>Power Module</b>	14-in-1 unit of IGBT/FWD in total IGBT Output power : 400 kVA (in total)
<b>IGBT chip</b>	Fuji Electric V-series (6th generation) System voltage : 1200 V
<b>Self Protection function</b>	IPM status sensing (temperature, voltage and failure information) and self protection by itself. Information communication with ECU.

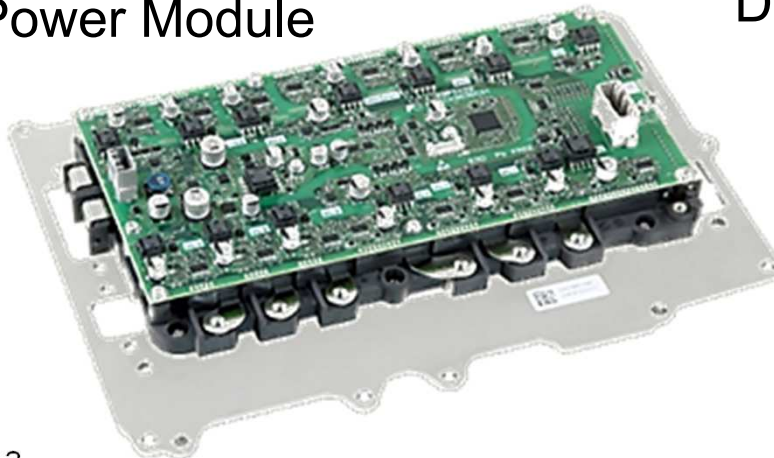
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# Conclusions

1. Design of Aluminum heat-sink
    - Developed a cooling structure that can be efficiently cooled
  2. Development high reliability solder material
    - Reliability is 7times longer compared with the Sn-Ag solder
    - Achieve a automotive quality used by Aluminum heat-sink
- ⇒We achieved direct liquid cooling module
- 30% volume, 60% weight reduction compared to products with conventional technologies

Front side

Intelligent Power Module



Back side

Direct Liquid Cooling Fin





*Thank you for your attention !*



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Where Fuji Electric locates*

*Sagrada Familia in Barcelona  
Where EVS held*